

ELECTRODEPOSITED COPPER FOIL GTS-MP

The *GTS-MP* foil is superior in mechanical properties such as high temperature elongation and is a new type of copper foil, which can be used for various products ranging from multilayer and high density PCB to flexible PCB.

An example of properties

| | Test item | Unit | GTS-MP | | | | Test methods | |
|---|---------------------------------|--|------------------------|------------------------|----------------------|----------------------|--------------|------------|
| | | | 12 μ m (1/3 oz) | 18 μ m (1/2 oz) | 35 μ m (1 oz) | 70 μ m (2 oz) | | |
| 1 | Thickness by weight | g/m ² | 108 | 152 | 284 | 573 | IPC-TM-650 | |
| 2 | Shiny-Side Surface Finish[Rz] | μ m | 1.85 | 1.85 | 1.85 | 1.85 | JIS B 0601 | |
| 3 | Matte-Side Surface Finish[Rz] | μ m | 6.5 | 7.5 | 9.5 | 12.5 | JIS B 0601 | |
| 4 | Tensile Strength | <i>At Room Temp.</i> | kg/mm ² | 35 | 33 | 31 | 29 | IPC-TM-650 |
| | | <i>At Elevated Temp. [180 °C]</i> | kg/mm ² | 20 | 19 | 18.5 | 18 | |
| 5 | Elongation | <i>At Room Temp.</i> | % | 5.5 | 8.5 | 17 | 30 | IPC-TM-650 |
| | | <i>At Elevated Temp. [180 °C]</i> | % | 11.5 | 13 | 15 | 17 | |
| 6 | Peel Strength*1) [FR4] | <i>Ordinary state</i> | kg/cm | 1.17 | 1.4 | 1.95 | 2.5 | JIS B 6481 |
| | | <i>after solder dip (260 °C 20sec)</i> | kg/cm | 1.17 | 1.4 | 1.95 | 2.5 | |
| 7 | Loss in Peel Strength in HCL*2) | % | 1.2 | 1.2 | 1 | 2 | JIS B 6481 | |

Note

*1) The prepreg kept by Furukawa Circuit Foil Taiwan Corporation was used for the test.

*2) Test method : 12% HCL, Room temperature, 30 min, specimen, 1mm wide.